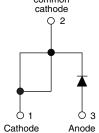


Vishay Semiconductors

Hyperfast Rectifier, 30 A FRED Pt®





TO-247AC modified

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|-------------------|--------------|
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| | │ |
| Ţ | |
| Ó 1 | О 3 |
| Cathode | Anode |

| PRODUCT SUMMARY | | | | | |
|----------------------------------|----------------------------|--|--|--|--|
| Package | TO-247AC modified (2 pins) | | | | |
| I _{F(AV)} | 30 A | | | | |
| V_{R} | 600 V | | | | |
| V _F at I _F | 2.6 V | | | | |
| t _{rr} typ. | See Recovery table | | | | |
| T _J max. | 175 °C | | | | |
| Diode variation | Single die | | | | |

FEATURES

- · Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- · Low leakage current
- Single diode device
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified according JEDEC-JESD47
- Halogen-free according to IEC 61249-2-21 definition (-N3 only)





HALOGEN FREE

DESCRIPTION/APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

| ABSOLUTE MAXIMUM RATINGS | | | | | | |
|---|-----------------------------------|-------------------------|-------------|-------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS | | |
| Peak repetitive reverse voltage | V_{RRM} | | 600 | V | | |
| Average rectified forward current | I _{F(AV)} | T _C = 116 °C | 30 | ^ | | |
| Non-repetitive peak surge current | I _{FSM} | T _J = 25 °C | 300 | A | | |
| Operating junction and storage temperatures | T _J , T _{Stg} | | - 65 to 175 | °C | | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|--|-------------------------------------|--|------|------|------|-------|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Breakdown voltage, blocking voltage | V _{BR} , V _R | Ι _R = 100 μΑ | 600 | - | - | | |
| Forward voltage | V _F | I _F = 30 A | - | 2.0 | 2.6 | V | |
| | | I _F = 30 A, T _J = 150 °C | - | 1.34 | 1.75 | | |
| Payaraa laakaga aurrant | 1 | V _R = V _R rated | - | 0.3 | 50 | | |
| Reverse leakage current I _R | | $T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$ | - | 60 | 500 | μΑ | |
| Junction capacitance | C _T | V _R = 600 V | - | 33 | - | pF | |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | - | 3.5 | - | nH | |



VS-30EPH06PbF, VS-30EPH06-N3

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| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | | |
|---|------------------|----------------------------------|--|------|------|-------|-----|--|
| PARAMETER | SYMBOL | TEST CO | MIN. | TYP. | MAX. | UNITS | | |
| | | $I_F = 1.0 \text{ A}, dI_F/dt =$ | $I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ | | 28 | 35 | | |
| Reverse recovery time | t _{rr} | T _J = 25 °C | | - | 31 | - | ns | |
| | | T _J = 125 °C | $I_F = 30 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$ | - | 77 | - | | |
| Dools woods on the out | I _{RRM} | T _J = 25 °C | | - | 3.5 | - | ^ | |
| Peak recovery current | | T _J = 125 °C | | - | 7.7 | - | A | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | | - | 65 | - | 200 | |
| | | T _J = 125 °C | | - | 345 | = | nC | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | | |
|---|-----------------------------------|--|--------------|---------|------------|------------------------|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | - 65 | - | 175 | °C | |
| Thermal resistance, junction to case per leg | R _{thJC} | | - | 0.5 | 0.9 | | |
| Thermal resistance, junction to ambient per leg | R _{thJA} | Typical socket mount | - | - | 70 | °C/W | |
| Thermal resistance, case to heatsink | R _{thCS} | Mounting surface, flat, smooth and greased | - | 0.4 | - | | |
| Weight | | | - | 6.0 | - | g | |
| vveignt | | | - | 0.22 | - | oz. | |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | |
| Marking device | | Case style TO-247AC modified | | 30EPH06 | | | |



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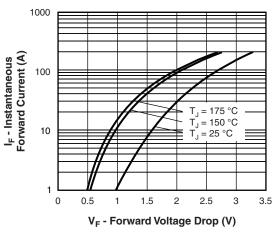


Fig. 1 - Typical Forward Voltage Drop Characteristics

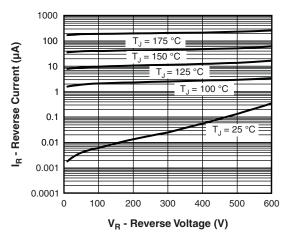


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

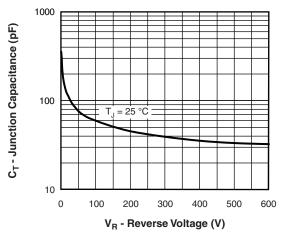


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

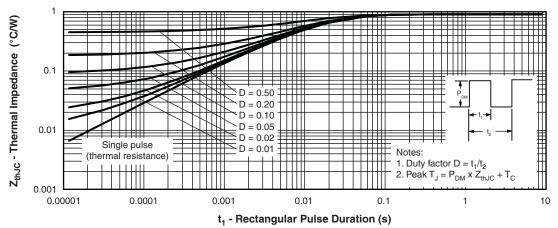


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics





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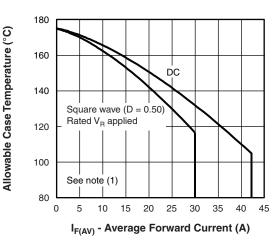


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

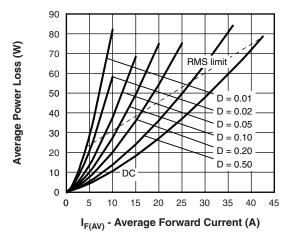


Fig. 6 - Forward Power Loss Characteristics

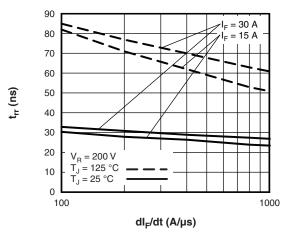


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

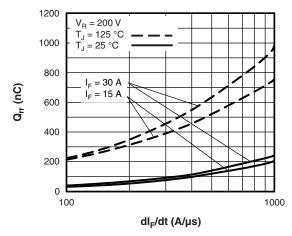


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{Rated } V_R \\ \end{array}$

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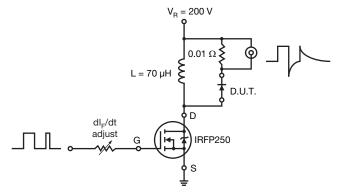
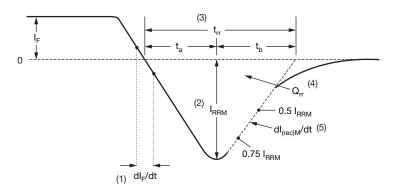


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

(5) dl_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

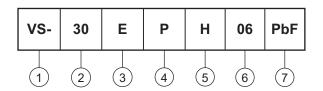
Fig. 10 - Reverse Recovery Waveform and Definitions

VS-30EPH06PbF, VS-30EPH06-N3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (30 = 30 A)

3 - Circuit configuration:

E = Single diode

4 - Package:

P = TO-247AC modified

5 - H = Hyperfast recovery

6 - Voltage rating (06 = 600 V)

7 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

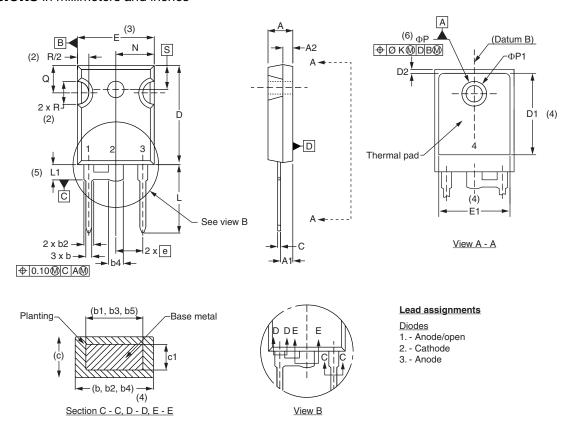
| ORDERING INFORMATION (Example) | | | | | | | |
|--------------------------------|------------------|------------------------|-------------------------|--|--|--|--|
| PREFERRED P/N | QUANTITY PER T/R | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION | | | | |
| VS-30EPH06PbF | 25 | 500 | Antistatic plastic tube | | | | |
| VS-30EPH06-N3 | 25 | 500 | Antistatic plastic tube | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | |
|----------------------------|-----------------------|--------------------------|--|--|--|
| Dimensions | | www.vishay.com/doc?95253 | | | |
| Part marking information | TO-247AC modified PbF | www.vishay.com/doc?95255 | | | |
| Part marking information | TO-247AC modified -N3 | www.vishay.com/doc?95442 | | | |



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DIMENSIONS in millimeters and inches



| SYMBOL | MILLIN | IETERS | INC | HES | NOTES |
|---------|--------|--------|-------|-------|-------|
| STWIBOL | MIN. | MAX. | MIN. | MAX. | NOTES |
| Α | 4.65 | 5.31 | 0.183 | 0.209 | |
| A1 | 2.21 | 2.59 | 0.087 | 0.102 | |
| A2 | 1.50 | 2.49 | 0.059 | 0.098 | |
| b | 0.99 | 1.40 | 0.039 | 0.055 | |
| b1 | 0.99 | 1.35 | 0.039 | 0.053 | |
| b2 | 1.65 | 2.39 | 0.065 | 0.094 | |
| b3 | 1.65 | 2.37 | 0.065 | 0.094 | |
| b4 | 2.59 | 3.43 | 0.102 | 0.135 | |
| b5 | 2.59 | 3.38 | 0.102 | 0.133 | |
| С | 0.38 | 0.86 | 0.015 | 0.034 | |
| c1 | 0.38 | 0.76 | 0.015 | 0.030 | |
| D | 19.71 | 20.70 | 0.776 | 0.815 | 3 |
| D1 | 13.08 | - | 0.515 | - | 4 |

| SYMBOL | MILLIN | IETERS | INCHES | | NOTES |
|---------|----------|--------|--------|-------|-------|
| STWIBOL | MIN. | MAX. | MIN. | MAX. | NOTES |
| D2 | 0.51 | 1.30 | 0.020 | 0.051 | |
| E | 15.29 | 15.87 | 0.602 | 0.625 | 3 |
| E1 | 13.72 | - | 0.540 | 1 | |
| е | 5.46 | BSC | 0.215 | BSC | |
| ΦК | 2. | 54 | 0.010 | | |
| L | 14.20 | 16.10 | 0.559 | 0.634 | |
| L1 | 3.71 | 4.29 | 0.146 | 0.169 | |
| N | 7.62 BSC | | 0 | .3 | |
| ΦР | 3.56 | 3.66 | 0.14 | 0.144 | |
| ФР1 | - | 6.98 | - | 0.275 | |
| Q | 5.31 | 5.69 | 0.209 | 0.224 | |
| R | 4.52 | 5.49 | 1.78 | 0.216 | |
| S | 5.51 | BSC | 0.217 | BSC | |

Notes

- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) ΦP to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



Legal Disclaimer Notice

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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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